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Glasgow Update

andrew stewart

15 March 2012

- Assembly received from Liverpool 13/03
  - Assembly attached to Single Chip Card and wire bonded.
  - Wire bonding successful but not trivial. A design change to the SCC could make the wire bonding more straight forward.
  - Reverse IV characteristic of sensor recorded (see plot on slide 4).
  - Test and tuning of Assembly currently under way.
  - Assembly will be taken to DESY Test-beam today (Thursday 15th) by Kate.
- Single Chip Cards
  - SCCs ready for distribution.
  - Need LEMO to PCB connector for sensor bias. These have been ordered. Expect delivery today or Friday (16th).

- Three functional ASICs and one Non-functional ASIC received from Bonn 13/03
  - Non-functional ASIC to be used for wire bonding trials
  - Functional ASICs to be used for SCC and wafer probing.
- Wafer Probing
  - Delay in wafer probe cards – will update delivery asap.
  - Delay in USBPix for wafer probing – no delivery date. Could be a couple more weeks.
- Bump bonding & flip chip at VTT
  - Electroplating kit was being repaired on Tuesday – will update asap.
  - Wafer V5ABC2H to be returned to Glasgow for shipping to Maurice.

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Liverpool Assembly – Sensor Reverse IV Characteristic.

Good agreement with measurement from Dean.

Micron Sensor IV Curve 13/03/2012

-450 -400 -350 -300 -250 -200 -150 -100 -50 0

0 -0.5 -1 -1.5 -2 -2.5 -3 -3.5 -4

Current (μA)

Voltage (V)